

*The Organizing Committee of 2021 7th International Workshop  
on Low Temperature Bonding for 3D Integration (LTB-3D)  
October 5-11, 2021, Online*

*delivers*

*Best Presentation Award*

*to*

*J. Liang<sup>1</sup>, D. Takatsuki<sup>1</sup>, Y. Shimizu<sup>2</sup>, M. Higashiwaki<sup>3</sup>, Y. Ohno<sup>2</sup>, Y. Nagai<sup>2</sup>, N. Shigekawa<sup>1</sup>;*

*<sup>1</sup> Osaka City University, <sup>2</sup> IMR, Tohoku University,*

*<sup>3</sup> National Institute of Information and Communications Technology*

*Fabrication of Ga<sub>2</sub>O<sub>3</sub>/Si direct bonding interface  
for high power device applications*



*Naoteru Shigekawa*  
*Naoteru Shigekawa, The Chair of LTB3D 2021*